

Docket No.: E0196.0006
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Letters Patent of:
Robert Bergmann et al.

Patent No.: 7,389,903

Confirmation No. 3112

Issued: June 24, 2008

For: **DEVICE AND METHOD FOR SOLDERING
CONTACTS ON SEMICONDUCTOR CHIPS**

**REQUEST FOR CERTIFICATE OF CORRECTION
PURSUANT TO 37 CFR 1.322**

Attention: Certificate of Correction Branch
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Upon reviewing the above-identified patent, Patentee noted a typographical error which should be corrected.

On the cover page, the inventor, Robert Bergmann's address should read
-- Regensburg (DE) --.

The error was not in the application as filed by applicant; accordingly no fee is required.

Transmitted herewith is a proposed Certificate of Correction effecting such amendment.
Patentee respectfully solicits the granting of the requested Certificate of Correction.

Dated: July 24, 2008

Respectfully submitted,

By 
Laura C. Brutman

Registration No.: 38,395
DICKSTEIN SHAPIRO LLP
1177 Avenue of the Americas
New York, New York 10036-2714
(212) 277-6500
Attorney for Applicant

**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

Page 1 of 1

PATENT NO. : 7,389,903
APPLICATION NO. : 10/812,830
ISSUE DATE : June 24, 2008
INVENTOR(S) : Robert Bergmann et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

(75) Inventors: **Robert Bergmann**, Regensburg (DE);
Holger Hubner, Baldham (DE)

MAILING ADDRESS OF SENDER (Please do not use customer number below):

Laura C. Brutman

DICKSTEIN SHAPIRO LLP

1177 Avenue of the Americas

New York, New York 10036-2714